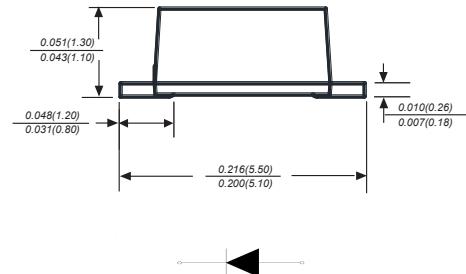
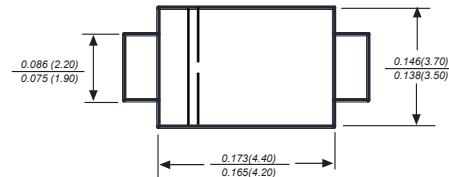




SURFACE MOUNT GENERAL PURPOSE SILICON RECTIFIER

Features

- ◆ For surface mounted applications
- ◆ Low profile package
- ◆ Glass Passivated Chip Junction
- ◆ Easy to pick and place
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives

SMBF

Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC UT BØ molded plastic body

Terminals : Solderable per MIL-STD-750, Method 2026A

Polarity : Polarity symbol marking on body

Mounting Position : Any

Weight : 0.002 ounce, 0.057 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

| Parameter | SYMBOLS | S3ABF | S3BBF | S3DBF | S3GBF | S3JBF | S3KBF | S3MBF | UNITS |
|--|-----------------------------------|--------------|--------------|--------------|--------------|--------------|--------------|--------------|-------|
| Marking Code | | MDD S3ABF | MDD S3BBF | MDD S3DBF | MDD S3GBF | MDD S3JBF | MDD S3KBF | MDD S3MBF | |
| Maximum repetitive peak reverse voltage | V _{RRM} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum RMS voltage | V _{RMS} | 35 | 70 | 140 | 280 | 420 | 560 | 700 | V |
| Maximum DC blocking voltage | V _{DC} | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| Maximum average forward rectified current at TL=65°C | I _(AV) | | | | | 3.0 | | | A |
| Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) | I _{FSM} | | | | | 100 | | | A |
| Maximum instantaneous forward voltage at 3.0A | V _F | | | | 1.10 | | | | V |
| Maximum DC reverse current TA=25°C at rated DC blocking voltage TA=125°C | I _R | | | | 5.0 | | | | μA |
| | | | | | 200.0 | | | | |
| Typical junction capacitance (NOTE 1) | C _J | | | | 45.0 | | | | pF |
| Typical thermal resistance (NOTE 2) | R _{θJA} | | | | 40.0 | | | | °C/W |
| Operating junction and storage temperature range | T _J , T _{Stg} | | | | -55 to +150 | | | | °C |

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. P.C.B. mounted with 0.5x0.5"(12.7x12.7mm) copper pad areas



Typical Characteristics

Fig.1 Forward Current Derating Curve

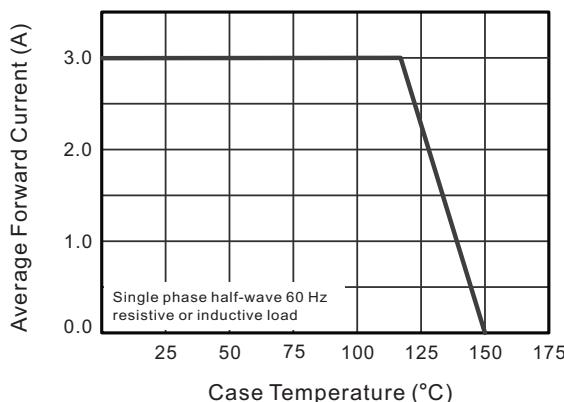


Fig.2 Typical Reverse Characteristics

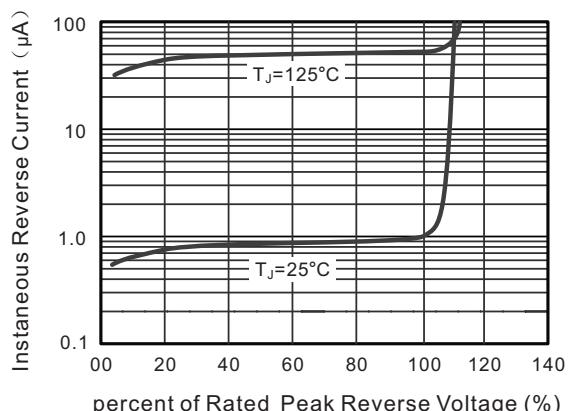


Fig.3 Typical Forward Characteristic

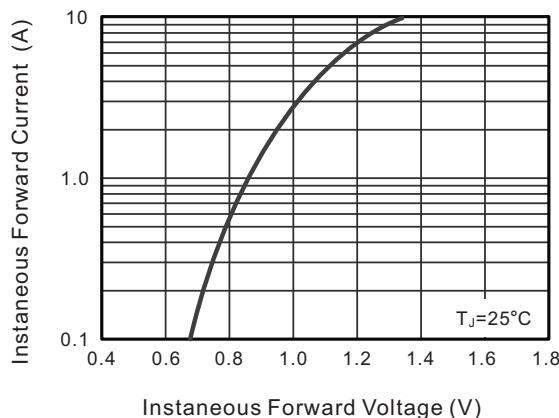


Fig.4 Typical Junction Capacitance

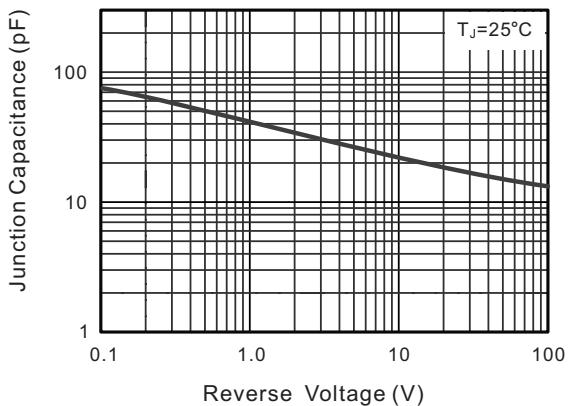
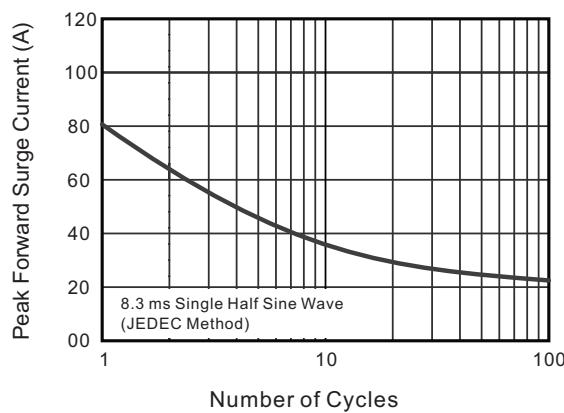
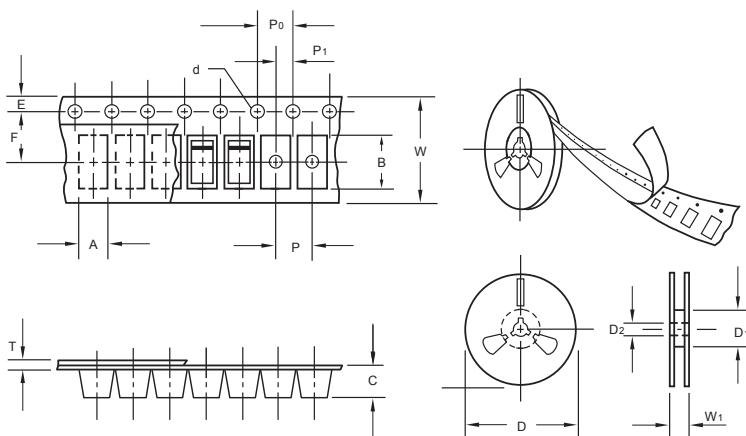


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

Packing information



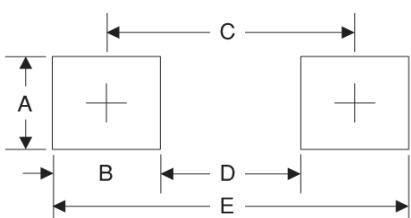
| Item | Symbol | Tolerance | SMF |
|---------------------------|----------------|-----------|--------|
| Carrier width | A | 0.1 | 3.81 |
| Carrier length | B | 0.1 | 5.61 |
| Carrier depth | C | 0.1 | 1.60 |
| Sprocket hole | d | 0.05 | 1.50 |
| 13" Reel outside diameter | D | 2.0 | 330.00 |
| 13" Reel inner diameter | D ₁ | min | 50.00 |
| Feed hole diameter | D ₂ | 0.5 | 13.00 |
| Sprocket hole position | E | 0.1 | 1.75 |
| Punch hole position | F | 0.1 | 5.50 |
| Punch hole pitch | P | 0.1 | 4.00 |
| Sprocket hole pitch | P ₀ | 0.1 | 4.00 |
| Embossment center | P ₁ | 0.1 | 2.00 |
| Overall tape thickness | T | 0.1 | 0.30 |
| Tape width | W | 0.3 | 12.00 |
| Reel width | W ₁ | 1.0 | 12.30 |

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

| PACKAGE | REEL SIZE | REEL (pcs) | COMPONENT SPACING (mm) | BOX (pcs) | INNER BOX (mm) | REEL DIA, (mm) | CARTON SIZE (mm) | CARTON (pcs) | APPROX. GROSS WEIGHT (kg) |
|---------|-----------|------------|------------------------|-----------|----------------|----------------|------------------|--------------|---------------------------|
| SMBF | 13" | 5,000 | 4.0 | 10,000 | 190*190*41 | 330 | 365*365*360 | 80,000 | 14.0 |

Suggested Pad Layout



| Symbol | Unit (mm) | Unit (inch) |
|--------|-----------|-------------|
| A | 2.54 | 0.100 |
| B | 1.8 | 0.071 |
| C | 4.8 | 0.189 |
| D | 3.0 | 0.118 |
| E | 6.6 | 0.260 |

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